

Silicon Carbide (SiC) MOSFET - 160 mohm, 1200 V, M1, D2PAK-7L

NTBG160N120SC1

Features

- Typ. $R_{DS(on)} = 160 \text{ m}\Omega$
- Ultra Low Gate Charge (typ. $Q_{G(tot)} = 33.8 \text{ nC}$)
- Low Effective Output Capacitance (typ. Coss = 50.7 pF)
- 100% Avalanche Tested
- $T_I = 175^{\circ}C$
- This Device is Halide Free and RoHS Compliant with exemption 7a, Pb–Free 2LI (on second level interconnection)

Typical Applications

- UPS
- DC-DC Converter
- Boost Inverter

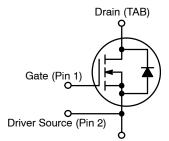
MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parameter			Symbol	nbol Value	
Drain-to-Source Voltage			V_{DSS}	1200	V
Gate-to-Source Voltaç	ge		V_{GS}	-15/+25	V
Recommended Operation T _C Values of Gate–Source Voltage		T _C < 175°C	V_{GSop}	-5/+20	V
Continuous Drain Current (Note 1)	Steady State	T _C = 25°C	I _D	19.5	A
Power Dissipation (Note 1)			P _D	136	W
Continuous Drain Current (Note 1)	Steady State	T _C = 100°C	I _D	13.7	Α
Power Dissipation (Note 1)			P _D	68	W
Pulsed Drain Current (Note 2) T _A = 25°C			I _{DM}	78	Α
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +175	°C
Source Current (Body Diode)			I _S	13.6	Α
Single Pulse Drain-to-Source Avalanche Energy ($I_L = 15.5 A_{pk}$, $L = 1 \text{ mH}$) (Note 3)			E _{AS}	120	mJ
Maximum Lead Temperature for Soldering, 1/8" from Case for 10 Seconds			TL	300	ç

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2. Repetitive rating, limited by max junction temperature.
- 3. E_{AS} of 120 mJ is based on starting $T_J = 25^{\circ}C$; L = 1 mH, $I_{AS} = 15.5$ A, $V_{DD} = 120$ V, $V_{GS} = 18$ V.

V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX
1200 V	224 mΩ @ 20 V	19.5 A



Power Source (Pins 3, 4, 5, 6, 7)

N-CHANNEL MOSFET



D2PAK-7L CASE 418BJ

MARKING DIAGRAM

AYWWZZ NTBG 160120SC1

A = Assembly Location

Y = Year WW = Work Week ZZ = Lot Traceability

NTBG160120SC1 = Specific Device Code

ORDERING INFORMATION

Device	Package	Shipping [†]
NTBG160N120SC1	D2PAK-7L	800 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

Table 1. THERMAL CHARACTERISTICS

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-to-Case (Note 1)	$R_{ heta JC}$	1.1	°C/W
Thermal Resistance Junction-to-Ambient (Note 1)	$R_{ hetaJA}$	40	°C/W

Table 2. ELECTRICAL CHARACTERISTICS (T_{.1} = 25°C unless otherwise stated)

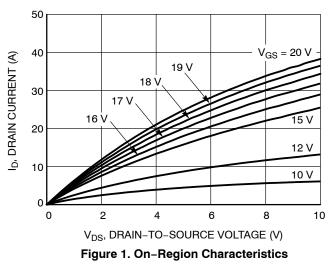
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
OFF CHARACTERISTICS			<u> </u>			
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 1 mA	1200			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /	I _D = 1 mA, refer to 25°C		0.7		V/°C
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 \text{ V}, \qquad T_J = 25^{\circ}\text{C}$			100	μΑ
		V _{DS} = 1200 V T _J = 175°C			1	mA
Gate-to-Source Leakage Current	I _{GSS}	$V_{GS} = +25/-15 \text{ V}, V_{DS} = 0 \text{ V}$			±1	μΑ
ON CHARACTERISTICS (Note 2)	•		_	-	•	
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D = 2.5 \text{ mA}$	1.8	3	4.3	V
Recommended Gate Voltage	V_{GOP}		-5		+20	V
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 20 V, I _D = 12 A, T _J = 25	5°C	160	224	mΩ
		V _{GS} = 20 V, I _D = 12 A, T _J = 17	75°C	239	365	mΩ
Forward Transconductance	9FS	V _{DS} = 10 V, I _D = 12 A		5.5		S
CHARGES, CAPACITANCES & GATE RES	ISTANCE		-			
Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1 MHz,		678		pF
Output Capacitance	C _{OSS}	V _{DS} = 800 V		50.7		
Reverse Transfer Capacitance	C _{RSS}			5.87		
Total Gate Charge	Q _{G(TOT)}	$V_{GS} = -5/20 \text{ V}, V_{DS} = 600 \text{ V},$		33.8		nC
Threshold Gate Charge	Q _{G(TH)}	I _D = 16 A		6.1		
Gate-to-Source Charge	Q _{GS}			11.6		
Gate-to-Drain Charge	Q_{GD}			9.6		1
Gate-Resistance	R_{G}	f = 1 MHz		1.39		Ω
SWITCHING CHARACTERISTICS	•		•	•	1	
Turn-On Delay Time	t _{d(ON)}	$V_{GS} = -5/20 \text{ V}, V_{DS} = 800 \text{ V},$		11	20	ns
Rise Time	t _r	I_D = 16 A, R_G = 6 Ω , Inductive Load		11	20	1
Turn-Off Delay Time	t _{d(OFF)}			15	27	1
Fall Time	t _f			7.4	15	1
Turn-On Switching Loss	E _{ON}			120		μJ
Turn-Off Switching Loss	E _{OFF}			28		1
Total Switching Loss	E _{TOT}			148		1
DRAIN-SOURCE DIODE CHARACTERIST	ics					•
Continuous Drain-Source Diode Forward Current	I _{SD}	$V_{GS} = -5 \text{ V}, T_J = 25^{\circ}\text{C}$			13.6	Α
Pulsed Drain-Source Diode Forward Current (Note 2)	I _{SDM}	$V_{GS} = -5 \text{ V}, T_J = 25^{\circ}\text{C}$			78	Α
	V_{SD}	V _{GS} = -5 V, I _{SD} = 6 A, T _J = 2		3.9	1	V

Table 2. ELECTRICAL CHARACTERISTICS (T_{.1} = 25°C unless otherwise stated) (continued)

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit		
DRAIN-SOURCE DIODE CHARACTERISTICS								
Reverse Recovery Time	t _{RR}	$V_{GS} = -5/20 \text{ V}, I_{SD} = 16 \text{ A},$ $dI_S/dt = 1000 \text{ A/}\mu\text{s}$		15		ns		
Reverse Recovery Charge	Q _{RR}			47		nC		
Reverse Recovery Energy	E _{REC}			3.9		μJ		
Peak Reverse Recovery Current	I _{RRM}]		6.6		Α		
Charge Time	Ta			7.0		ns		
Discharge Time	Tb			7.4		ns		

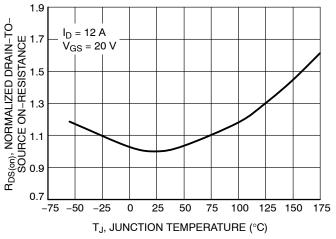
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS



OL NAMA 3.5 OL NAMA 3.0 OL NAMA 3.5 OL NA

Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage



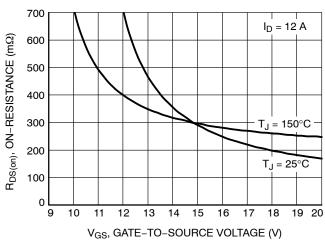
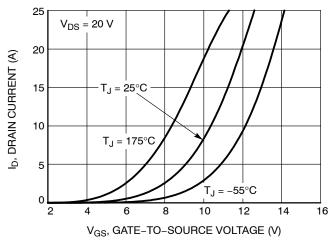


Figure 3. On–Resistance Variation with Temperature

Figure 4. On-Resistance vs. Gate-to-Source Voltage



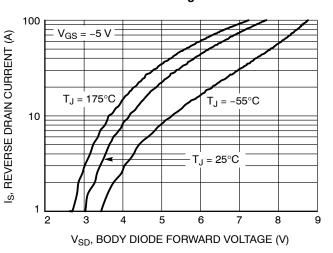


Figure 5. Transfer Characteristics

Figure 6. Diode Forward Voltage vs. Current

TYPICAL CHARACTERISTICS (continued)

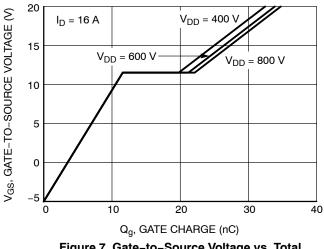


Figure 7. Gate-to-Source Voltage vs. Total Charge

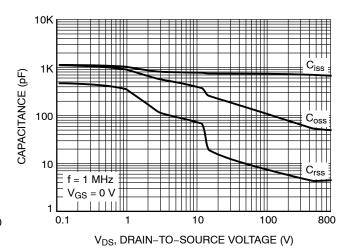


Figure 8. Capacitance vs. Drain-to-Source Voltage

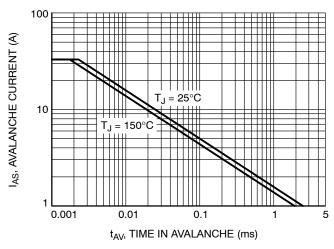


Figure 9. Unclamped Inductive Switching Capability

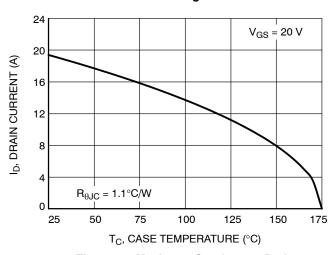


Figure 10. Maximum Continuous Drain Current vs. Case Temperature

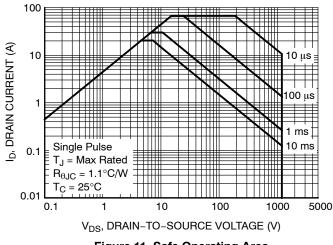


Figure 11. Safe Operating Area

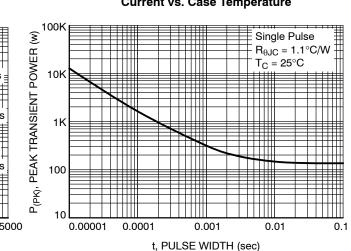


Figure 12. Single Pulse Maximum Power Dissipation

TYPICAL CHARACTERISTICS (continued)

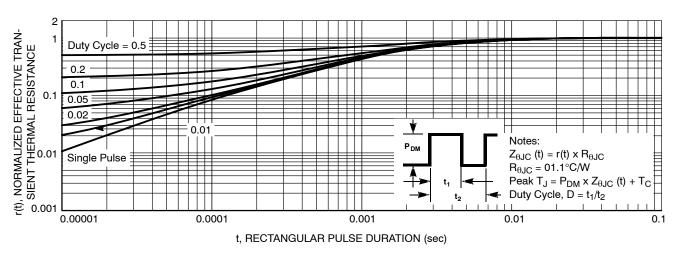


Figure 13. Junction-to-Ambient Transient Thermal Response Curve

Α

D

aaa | B | A |M

3.20 MIN

E1

D²PAK7 (TO-263-7L HV) CASE 418BJ **ISSUE B**

DATE 16 AUG 2019

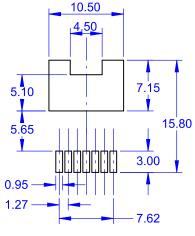
NOTES:

- A. PACKAGE CONFORMS TO JEDEC TO-263 VARIATION CB EXCEPT WHERE NOTED. B. ALL DIMENSIONS ARE IN MILLIMETERS.
- OUT OF JEDEC STANDARD VALUE.

 D. DIMENSION AND TOLERANCE AS PER ASME Y14.5-2009.

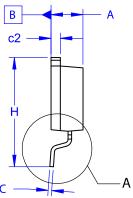
 E. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.

DIM	MILLIMETERS				
DIM	MIN	NOM	MAX		
Α	4.30	4.50	4.70		
A 1	0.00	0.10	0.20		
b2	0.60	0.70	0.80		
b	0.51	0.60	0.70		
С	0.40	0.50	0.60		
c2	1.20	1.30	1.40		
D	9.00	9.20	9.40		
D1	6.15	6.80	7.15		
Е	9.70	9.90	10.20		
E1	7.15	7.65	8.15		
е	~	1.27	~		
Н	15.10	15.40	15.70		
L	2.44	2.64	2.84		
L1	1.00	1.20	1.40		
L3	~	0.25	~		
aaa	~	~	0.25		



LAND PATTERN RECOMMENDATION





GENERIC MARKING DIAGRAM*

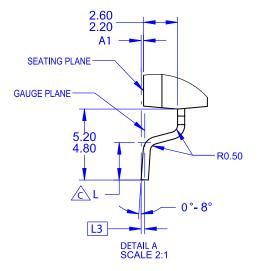
D1



XXXX = Specific Device Code = Assembly Location

= Year WW = Work Week G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "=", may or may not be present. Some products may not follow the Generic Marking.



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